

L Number	Hits	Search Text	DB	Time stamp
2	1	("5984691").PN.	USPAT	2002/08/10 11:40
1	63	flexible with (pth or (plated adj through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:47
3	1	("4954878").PN.	USPAT	2002/08/10 12:11
4	551	(substrate with (circuit adj card))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:37
5	0	"L54" and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:12
6	20	((substrate with (circuit adj card))) and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:43
7	6	((substrate with (circuit adj card))) and ((pwb or (printed adj wiring adj board)) with (circuit adj card))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:33
8	0	interposer and ((pwb or (printed adj wiring adj board)) with (circuit adj card))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:33
9	53	((pwb or (printed adj wiring adj board)) with (circuit adj card))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:34
10	14	((pwb or (printed adj wiring adj board)) with (circuit adj card)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 12:34
11	1	("4954878").PN.	USPAT	2002/08/10 13:18
12	1	("5984691").PN.	USPAT	2002/08/10 13:43
13	15	(Plated adj (hole or via)) with (copper and solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 13:53
14	25	((Plated adj (hole or via)) or pth) and (((hole or via) near (fill or filled)) with solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:10
15	8	((Plated adj (hole or via)) or pth) and (((hole or via) near (fill or filled)) with solder)) and ((copper or cu) with ((Plated adj (hole or via)) or pth))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:21
16	1	("4954878").PN.	USPAT	2002/08/10 14:30
17	1	("5248262").PN.	USPAT	2002/08/10 14:30
18	27	5248262.URPN.	USPAT	2002/08/10 14:31
19	11	geometry with (pth or (plated adj through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:49

20	5	(slant or slope) adj (pth or (plated adj through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:50
22	3369	(slant or slope) with (via or pth or (through adj hole))	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:51
24	37	((slant or slope) near (via or pth or (through adj hole))) and (chip or die)	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:52
23	363	(slant or slope) near (via or pth or (through adj hole))	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 14:54
25	44	(slant or slope) near (pth or (through adj hole))	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 15:00
26	57	("v") near (pth or (through adj hole))	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/10 15:01